

MA4X160A (MA160A)

Silicon epitaxial planar type

For switching circuits

■ Features

- Two isolated elements contained in one package, allowing high-density mounting
- Centrosymmetrical wiring, allowing to free from the taping direction
- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25^{\circ}\text{C}$

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	80	V
Repetitive peak reverse voltage		V_{RRM}	80	V
Forward current (Average)	Single	$I_{F(AV)}$	100	mA
	Series		75	
Repetitive peak forward current	Single	I_{FRM}	225	mA
	Series		170	
Non-repetitive peak forward surge current *	Single	I_{FSM}	500	mA
	Series		375	
Junction temperature		T_j	150	$^{\circ}\text{C}$
Storage temperature		T_{stg}	-55 to +150	$^{\circ}\text{C}$

Note) *: $t = 1\text{ s}$

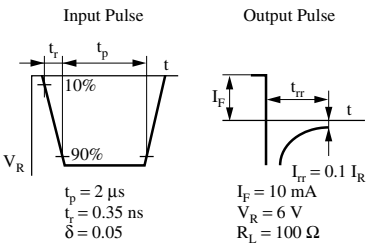
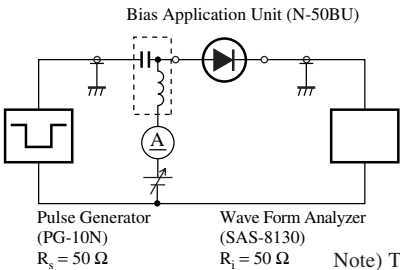
■ Electrical Characteristics $T_a = 25^{\circ}\text{C} \pm 3^{\circ}\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100\text{ mA}$		0.95	1.20	V
Reverse voltage	V_R	$I_R = 100\text{ }\mu\text{A}$	80			V
Reverse current	I_R	$V_R = 75\text{ V}$			0.1	μA
Terminal capacitance	C_t	$V_R = 0\text{ V}, f = 1\text{ MHz}$		0.9	2.0	pF
Reverse recovery time *	t_{rr}	$I_F = 10\text{ mA}, V_R = 6\text{ V}$ $I_{rr} = 0.1 I_R, R_L = 100\text{ }\Omega$			3	ns

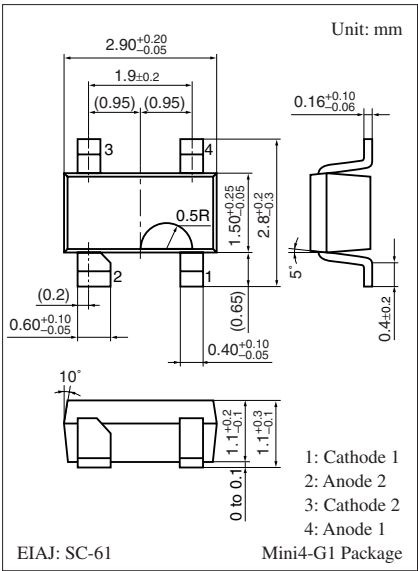
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

3. *: t_{rr} measurement circuit

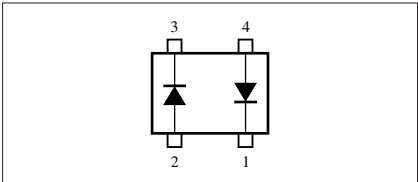


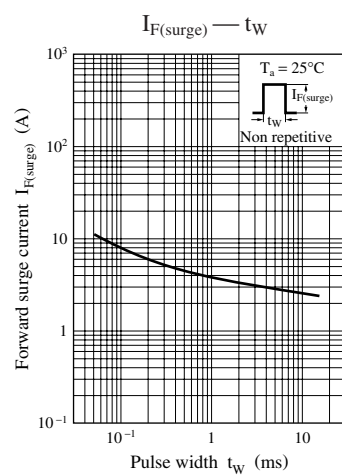
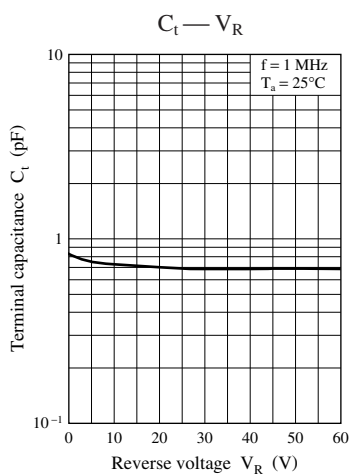
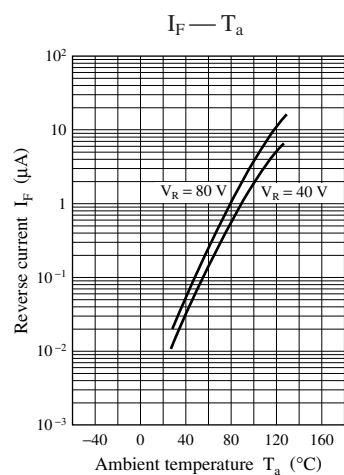
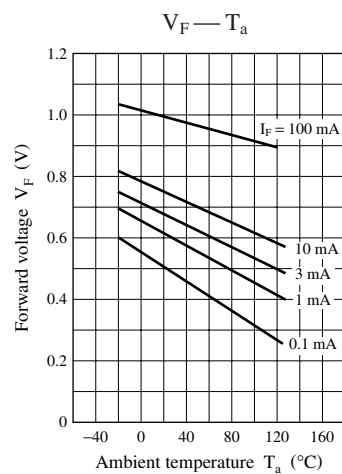
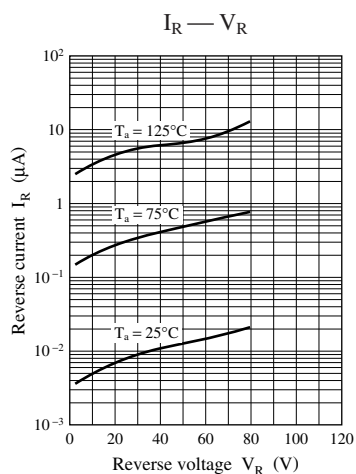
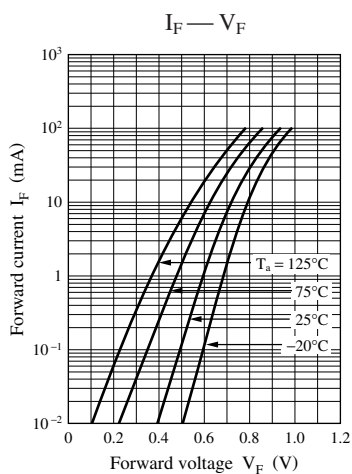
Note) The part number in the parenthesis shows conventional part number.



Marking Symbol: M1E

Internal Connection





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